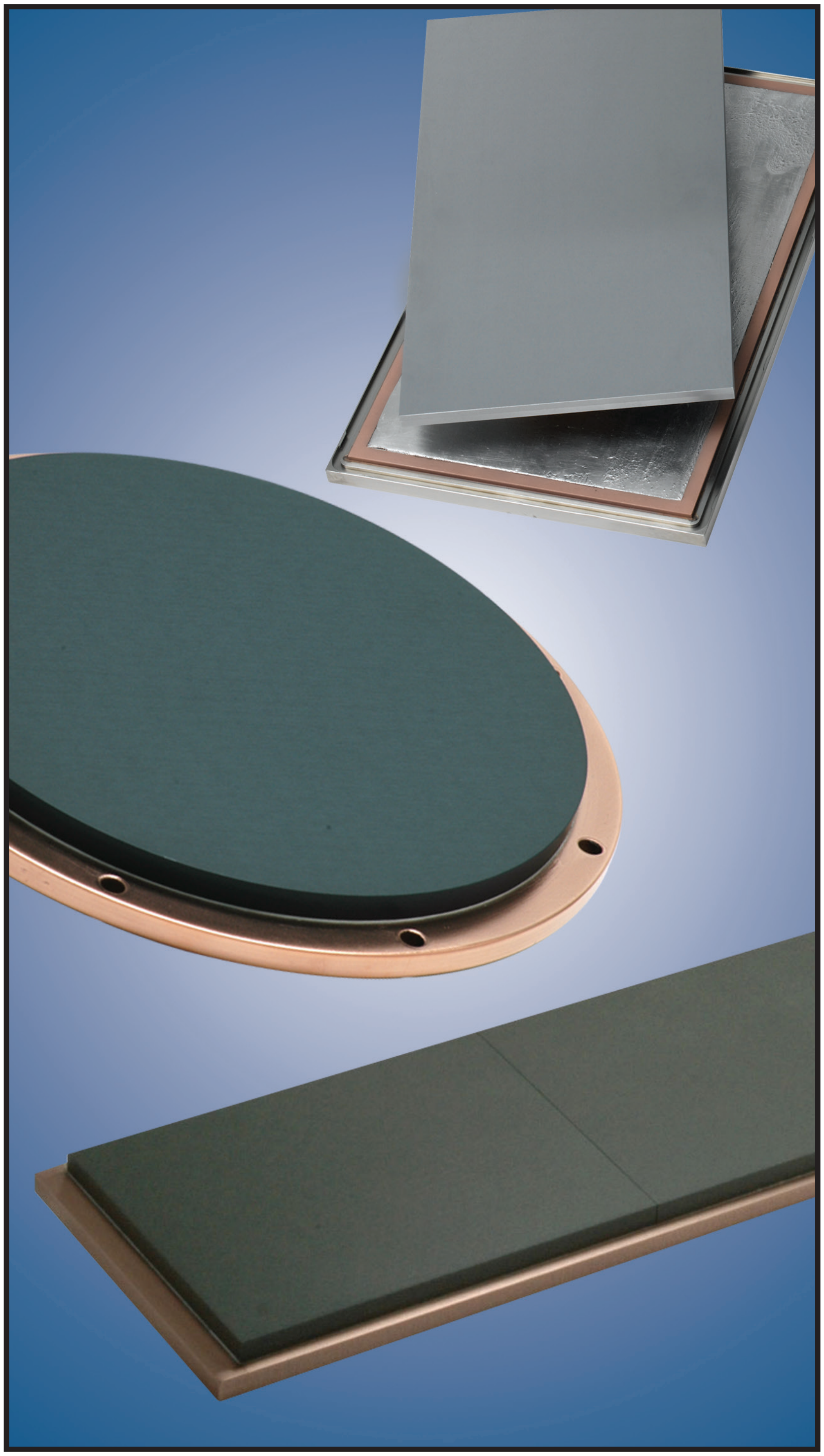
Elastomer Bonding

Service



Kurt J. Lesker Company

MATERIALS™ DIVISION

Applications

- Sputtering target and backing plate bonding

Features

- Thorough Bond Coverage
- Provides Support for Fragile Target Materials
- Higher Temperature Capability Than Indium Bonding
- Bonded at Low Temperatures (50°C - 100°C)
- NASA “A” rating (undergoes less than a 1% total mass change at 150°C at 1 x 10^{-7}Torr for 24 hrs)
- Does not absorb any moisture
- Equipped to handle cycles between vacuum and atmosphere

Bonding Process

- Target bonding surface may be coated prior to bonding to improve adhesion
- Bonding surfaces primed and elastomer mixture prepared for complete bond coverage
- Accurate alignment of target on backing plate
- Elastomer bonds are shear tested
- Bonded target assemblies are cleaned and ready for use in vacuum

Options

- Wide range of sizes and shapes
- Multi-tile assemblies
- Complex backing plate configurations
- Compatible with most target materials

Specifications

Maximum Operating Temperature	250°C
Thermal Conductivity	54 W/m·K
Coefficient of Thermal Expansion	2.2 x 10^{-4} K^{-1}
Electrical Resistivity	0.0476 Ohm-cm
Bond Coverage	>98%
Bond Line Thickness	0.010"-0.025"

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Kurt J. Lesker Company
United States - salesus@lesker.com
412.387.9200
800.245.1656

Kurt J. Lesker Canada Inc.
Canada - salescan@lesker.com
416.588.2610
800.465.2476

Kurt J. Lesker Company Ltd.
EMEIA - EMEIAsales@lesker.com
+44 (0) 1424 458100

Kurt.Lesker (Shanghai) Trading Company
科特·莱思科(上海)商贸有限公司
Asia - salesasia@lesker.com
+86 21 50115900